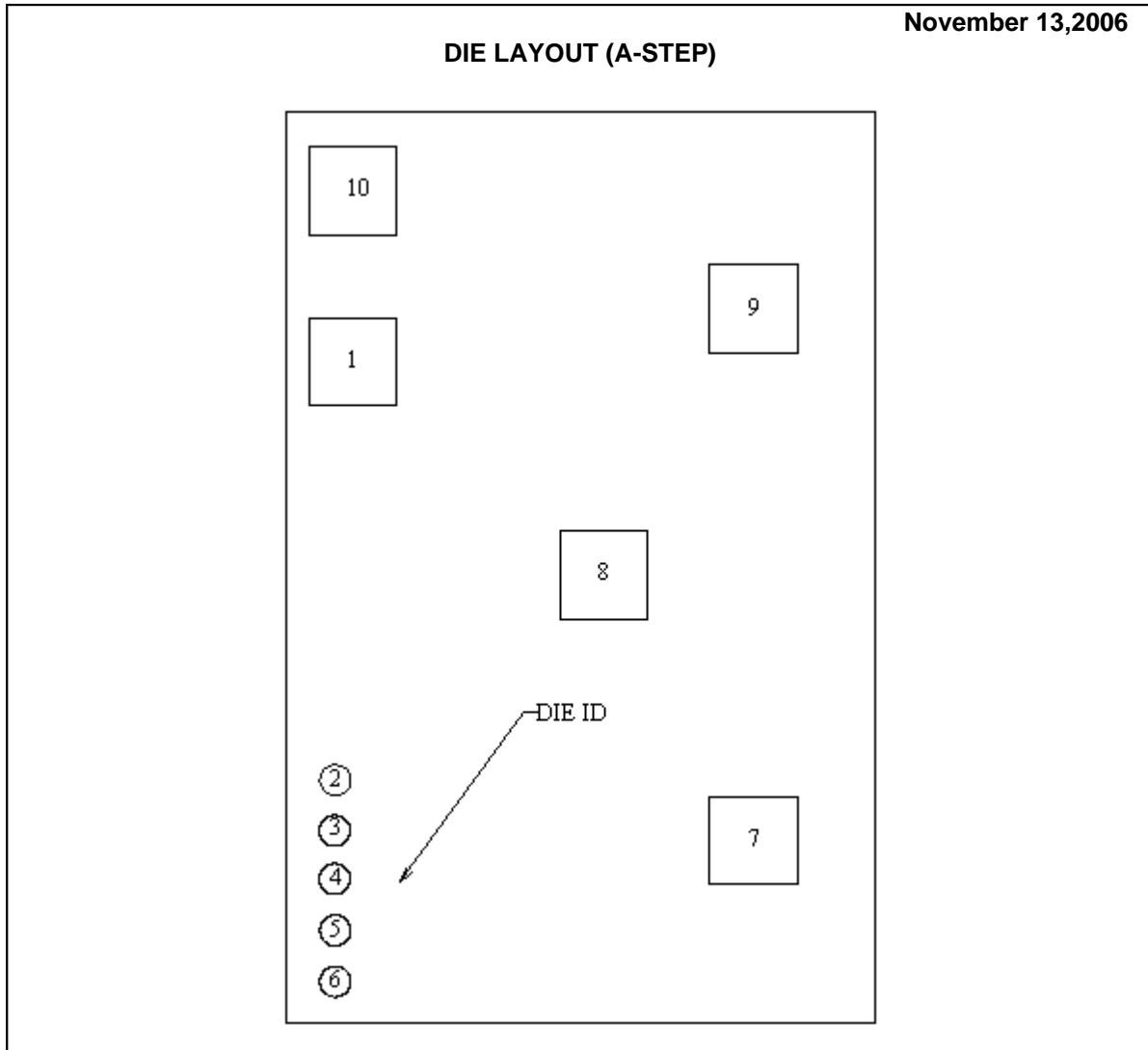


**LM1086-ADJ MDC MWC
1.5A LOW DROPOUT POSITIVE REGULATORS**



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|---|-----------------------------|---------------|
| Physical Die Identification | LM1086A-ADJ | Bond Pad Opening Size (min) | 270µm x 370µm |
| Die Step | A | Bond Pad Metalization | ALUMINUM |
| Physical Attributes | | Passivation | VOM NITRIDE |
| Wafer Diameter | 150mm | Back Side Metal | TINIAG |
| Die Size (Drawn) | 1803µm x 2794µm 71.0mils x 110.0mils | Back Side Connection | GND |
| Thickness | 330µm Nominal | | |
| Min Pitch | 150µm Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

| SIGNAL NAME | PAD# NUMBER | X/Y COORDINATES | | PAD SIZE | | |
|----------------|----------------|-----------------|-------|----------|---|-----|
| | | X | Y | X | Y | |
| ADJ/GND | 1 | -699 | 630 | 270 | x | 270 |
| NC | 2 | -754 | -655 | 91 | x | 91 |
| NC | 3 | -754 | -806 | 91 | x | 91 |
| NC | 4 | -754 | -956 | 91 | x | 91 |
| NC | 5 | -754 | -1115 | 91 | x | 91 |
| NC | 6 | -754 | -1271 | 91 | x | 91 |
| OUTPUT | 7 | 531 | -839 | 270 | x | 270 |
| INPUT | 8 | 71 | -23 | 270 | x | 270 |
| OUTPUT | 9 | 531 | 791 | 270 | x | 270 |
| OUTPUT | 10 | -699 | 1155 | 270 | x | 270 |

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